

9 Micron Metal Gate CMOS Family

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Features

- Metal Gate Process
- 13 μm Metal Pitch
- 16 Volts Maximum Operating Voltage
- Simple Process (7 masks)
- Very Short Cycle Time
- Very High Yield

Process Parameters

Process Parameters	9 μ m	Units
Metal pitch (width/space)	8 / 5	μm
Contact	8 x 8	μm
Gate geometry	9	μm
P-well junction depth	9	μm
N+ junction depth	2.4	μm
P+ junction depth	2.6	μm
Gate oxide thickness	1050	Å

Description

The 9 μ m process is a CMOS process with an operating voltage range from 5 to 16 volts. The gate material is metal; which is common in many mature designs. An advantage of this process is its simplicity and its short cycle time.

Resistances (Ω **/sq.)**

	9 Micron - 15 volts			
	min.	typ.	max.	
Pwell		1500		
N+	35	45	55	
P+	40	70	100	
Metal I		0.038		

MOSFET Electrical Parameters

	9 MICRON - 15 volts							
Electrical Parameters	min.	N Channel typ.	l max.	min.	P Channe typ.	l max.	Units	Conditions
Vt (50x9µm)	1.0	1.3	1.6	1.6	1.9	2.2	V	saturation
lds (50x9μm)		200			60		μA/μm	Vds=Vgs=3v
Gainβ (50x9μm)		700			200		μΑ/V ²	
Bvdss	20	28		20	30		V	lds=1μA
Field Threshold		23			20		V	lds = 1µA
L Effective		5.2			4.8		μm	L drawn = 9µm

Notes: